

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-3. (Canceled)

4. (Previously presented) The sheet-like board member as defined in claim 10, further comprising:

a wiring disposed on said second planar surface, wherein the mask is formed on a region corresponding to the wiring integrally connected to one or more of the first pads.

5. (Previously presented) The sheet-like board member as defined in claim 10, wherein the first pads are bonding pads or pads on which solder balls are to be fixed.

6. (Previously presented) The sheet-like board member as defined in claim 10, wherein the conductive coating film is disposed in the semiconductor element mount region to form a die pad.

7. (Previously presented) The sheet-like board member as defined in claim 10, wherein the conductive coating film is disposed on the second planar surface to form a die pad and/or outer lead electrode.

8. (Previously presented) The sheet-like board member as defined in claim 7, wherein a passive element to be placed on the die pad comprises a chip resistor or a chip capacitor.

9. (Canceled)

10. (Currently amended) A sheet-like board member comprising:

a first planar surface;

a second planar surface disposed opposite to the first surface, said second planar surface including at least one unit each having a plurality of semiconductor element mount regions defined thereon;

a mask disposed on the second planar surface and having [[a]] respective patterns corresponding to a plurality of first pads formed in or in the vicinity of the semiconductor element mount regions, said mask comprising a conductive film, and

guide holes into which guide pins are inserted,

wherein each unit includes a plurality of first pads defined by the respective patterns in the unit and a plurality of die pads defined by the respective semiconductor element mount regions in the unit.

11. (Previously presented) The sheet-like board member as defined in claim 10, wherein the sheet-like board member is formed from a conductive foil, and the conductive film is formed of a material different from that of the conductive foil.

12. (Currently amended) A sheet-like board member comprising:

a first planar surface;

a second planar surface disposed opposite to the first planer surface, the second surface including at least one unit each of which includes ~~[[; a]]~~ protuberances and semiconductor mount regions formed on said second planar surface ; and

guide holes into which guide pins are inserted,

wherein the protuberances define ~~comprises~~ a plurality of first pads in or in the vicinity of [[a]] the semiconductor element mount regions defined on the second planar surface , and

wherein each unit includes a plurality of die pads defined by the respective semiconductor mount regions in the unit.

13. (Previously presented) The sheet-like board member as defined in claim 12, wherein the protuberance comprises wirings integrally formed with the first pads.

14. (Previously presented) The sheet-like board member as defined in claim 13, wherein the protuberance comprises second pads integrally formed with the wirings.

15. (Previously presented) The sheet-like board member as defined in claim 12, wherein the first pads comprise bonding pads, or pads on which solder balls or bumps are mounted.

16. (Previously presented) The sheet-like board member as defined in claim 12, wherein the protuberance comprises die pads provided in the semi-conductor element mount region.

17. (Previously presented) The sheet-like board member as defined in claim 12, wherein the protuberance comprises die pads and/or outer lead electrodes.

18 (Currently amended) The sheet-like board member as defined in claim 17, wherein a passive element ~~to be~~ is disposed on the die pad comprises a chip resistor or chip capacitor.

19. (Canceled)

20. (Previously presented) The sheet-like board member as defined in claim 12 comprising protuberances arranged in a plurality of patterns as a unit, wherein the unit is arranged in a matrix pattern on the sheet-like board member.

21. (Previously presented) The sheet-like board member as defined in claim 12, wherein the sheet-like board member comprises mainly Cu, Al, an Fe-Ni alloy, a Cu-Al multi-layered member, or an Al-Cu-Al multi-layered member.

22. (Previously presented) The sheet-like board member as defined in claim 12 comprising a conductive coating film formed of material different from that of the protuberance and formed on an upper surface of the protuberance.

23. (Previously presented) The sheet-like board member as defined in claim 12, wherein a side surface of the protuberance has an anchoring structure.

24. (Previously presented) The sheet-like board member as defined in claim 12, further comprising:

a conductive film comprising an anvil-shaped structure in the vicinity of a top surface of the protuberance.

25. (Previously presented) The sheet-like board member as defined in claim 12 comprising a conductive film on the protuberance, wherein the conductive film comprises Ni, Au, Ag or Pd.

26. (Currently amended) A sheet-like board member comprising:

a planar surface defining at least one unit;

a sheet-like front side of predetermined thickness which is provided on the planar surface;

a plurality of first pads formed in each unit in or in the vicinity of [[a]] semiconductor element mount regions defined in each unit on the planar surface;

protuberances in each unit formed on said planar surface and ~~include~~ including wirings integrally formed with the first pads, said plurality of first pads and said protuberances formed within an abutting region defined on said planar surface, said abutting region provided to contact with an upper metal mold; and

guide holes into which guide pins are inserted

wherein each unit includes a plurality of die pads defined by the respective semiconductor mount regions in the unit.

27-31. (Canceled)

32. (Previously presented) The sheet-like board member of claim 26, wherein said planar surface having the protuberances, some of which semiconductor elements are disposed thereon, are all encapsulated in plastic.

33. (Currently amended) A sheet-like board member comprising:  
a first planar surface;  
a second planar surface disposed opposite to the first surface, said second planar surface having [[a]] at least one unit each of which has semiconductor element mount regions defined thereon;

a mask for etching disposed on the second planar surface and having [[a]] patterns corresponding to a plurality of first pads formed in or in the vicinity of the semiconductor element mount regions, wherein each unit comprises a plurality of the patterns, and  
guide holes into which guide pins are inserted,  
wherein each unit includes a plurality of die pads defined by the respective semiconductor mount regions in the unit.

34. (Previously presented) The sheet-like board member as defined in claim 33, wherein the mask comprises a photoresist.

35. (Previously presented) The sheet-like board member as defined in claim 33, wherein the mask comprises a conductive film.

36. (Previously presented) The sheet-like board member as defined in claim 33, further comprising:

a wiring disposed on said second planar surface, wherein the mask is formed on a region corresponding to the wiring integrally connected to one or more of the first pads.

37. (Previously presented) The sheet-like board member as defined in claim 33, wherein the first pads are bonding pads or pads on which solder balls are to be fixed.

38. (Previously presented) The sheet-like board member as defined in claim 33, wherein the conductive coating film is disposed in the semiconductor element mount region to form a die pad.

39. (Previously presented) The sheet-like board member as defined in claim 33, wherein the conductive coating film is disposed on the second planar surface to form a die pad and/or outer lead electrode.

40. (Currently amended) The sheet-like board member as defined in claim 39, wherein a passive element ~~to be placed~~ is on the die pad comprises a chip resistor or a chip capacitor.

41. (Canceled)

42. (Previously presented) The sheet-like board member as defined in claim 33, wherein the sheet-like board member comprises a pressed metal.

43. (Previously presented) The sheet-like board member as defined in claim 33, wherein the sheet-like board member is formed from a conductive foil, and the conductive film is formed of a material different from that of the conductive foil.

44. (Previously presented) The sheet-like board member as defined in claim 10 or 33 wherein the sheet-like board is partially etched in an area not covered by the mask.

45. (Previously presented) The sheet-like board member as defined in claim 10 wherein a positioning mark is provided on the sheet-like board member.

46. (Previously presented) The sheet-like board member as defined in claim 45 wherein the positioning mark is formed by partially etching the sheet-like board member.

47. (Canceled)

48. (Previously presented) The sheet-like board member as defined in claim 10 or 33 wherein the sheet-like board is partially etched in an area not covered by the conductive film.

49. (Previously presented) The sheet-like board member as defined in claim 12 wherein a positioning mark is provided on the sheet-like board member.

50. (Previously presented) The sheet-like board member as defined in claim 49 wherein the positioning mark is formed by partially etching the sheet-like board member.

51. (Canceled)

52. (Previously presented) The sheet-like board member as defined in claim 12 comprising a conductive film formed on the protuberance.

53. (Previously presented) The sheet-like board member as defined in claim 12 wherein an Ag plating is formed on the protuberance.

54. (Previously presented) The sheet-like board member as defined in claim 26 wherein a positioning mark is provided on the sheet-like board member.

55. (Previously presented) The sheet-like board member as defined in claim 54 wherein the positioning mark is formed by partially etching the sheet-like board member.

56. (Canceled)

57. (Previously presented) The sheet-like board member as defined in claim 33 wherein the sheet-like board is partially etched in area not covered by the mask.

58. (Previously presented) The sheet-like board member as defined in claim 33 wherein a positioning mark is provided on the sheet-like board member.

59. (Previously presented) The sheet-like board member as defined in claim 58 wherein the positioning mark is formed by partially etching the sheet-like board member.

60. (Canceled)

61. (Currently amended) A method of manufacturing a semiconductor device comprising:

preparing a sheet-like board member as defined in claim 10 ~~any one of claims 10, 12, 26, 33 and 44-60~~ ;

partially etching the second planar surface of the sheet-like member so as to form the first pads;

disposing a circuit element onto a portion on the sheet-like board member;

molding a surface of the sheet-like board member by an insulating resin so that the sheet-like board member is covered.



62. (Previously presented) The method of manufacturing a semiconductor device according to claim 61 wherein the sheet-like board member is fixed by means of vacuum suction.

63. (Previously presented) A method of manufacturing a semiconductor device comprising:  
preparing a sheet-like board member as defined in any one of claims 12 and 26;  
disposing a circuit element onto a portion of the protuberances of the sheet-like board member;  
molding a surface of the sheet-like board member by an insulating plastic so that the sheet-like board member is covered.

64. (Previously presented) The method of manufacturing a semiconductor device according to claim 63 wherein the sheet-like board member is fixed by means of vacuum suction.

65. (Previously presented) The sheet-like board member of claim 10 including a wiring continuously extended from a land.

66. (Previously presented) The sheet-like board member of claim 12 including a wiring continuously extended from a land.

67. (Previously presented) The sheet-like board member of claim 26 including a wiring continuously extended from a land.

68. (Previously presented) The sheet-like board member of claim 33 including a wiring continuously extended from a land.

69. (Previously presented) The sheet-like board member of claim 10 wherein the sheet-like board member is made of a metal.

70. (Previously presented) The sheet-like board member of claim 10 wherein a wiring extends continuously from the first pad.

71. (Previously presented) The sheet-like board member of claim 12 wherein the sheet-like board member is made of a metal.

72. (Previously presented) The sheet-like board member of claim 12 wherein a wiring extends continuously from the first pad.

73. (Previously presented) The sheet-like board member of claim 26 the wiring extend continuously from the first pad.

74. (Previously presented) The sheet-like board member of claim 33 wherein the sheet-like board member is made of a metal.

75. (Previously presented) The sheet-like board member of claim 33 wherein a wiring extends continuously from the first pad.